

March 2008

NC7SZ00

TinyLogic® UHS 2-Input NAND Gate

Features

- Space saving SOT23 or SC70 5-lead package
- Ultra small MicroPak™ leadless package
- Ultra High Speed; t_{PD} 2.4ns typ. into 50pF at 5V V_{CC}
- High Output Drive; ±24mA at 3V V_{CC}
- Broad V_{CC} Operating Range; 1.65V–5.5V
- Matches the performance of LCX when operated at 3.3V V_{CC}
- Power down high impedance inputs/output
- Overvoltage tolerant inputs facilitate 5V to 3V translation
- Patented noise/EMI reduction circuitry implemented

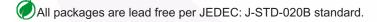
General Description

The NC7SZ00 is a single 2-Input NAND Gate from Fairchild's Ultra High Speed Series of TinyLogic $^{\tiny (8)}$. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a broad V_{CC} operating range. The device is specified to operate over the 1.65V to 5.5V V_{CC} operating range. The inputs and output are high impedance when V_{CC} is 0V. Inputs tolerate voltages up to 6V independent of V_{CC} operating voltage.

Ordering Information

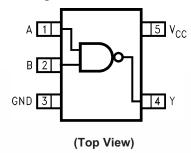
Order Number	Package Number	Product Code Top Mark	Package Description	Supplied As
NC7SZ00M5X	MA05B	7Z00	5-Lead SOT23, JEDEC MO-178, 1.6mm	3k Units on Tape and Reel
NC7SZ00P5X	MAA05A	Z00	5-Lead SC70, EIAJ SC-88a, 1.25mm Wide	3k Units on Tape and Reel
NC7SZ00L6X	MAC06A	YY	6-Lead MicroPak, 1.0mm Wide	5k Units on Tape and Reel

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

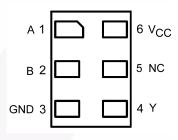


Connection Diagram

Pin Assignments for SC70 and SOT23

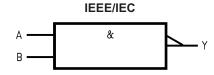


Pad Assignment for MicroPak



(Top Thru View)

Logic Symbol



Function Table

 $Y = \overline{AB}$

Inp	uts	Output
Α	В	Y
L	L	Н
L	Н	Н
Н	L	Н
Н	Н	L

H = HIGH Logic Level L = LOW Logic Level

Pin Description

Pin Names	Description
A, B	Inputs
Υ	Output
NC	No Connect

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	-0.5V to +6V
V _{IN}	DC Input Voltage	-0.5V to +6V
V _{OUT}	DC Output Voltage	-0.5V to +6V
lik	DC Input Diode Current @ V _{IN} < -0.5V @ V _{IN} > 6V	–50mA +20mA
I _{OK}	DC Output Diode Current @ V _{OUT} < -0.5V @ V _{OUT} > 6V, V _{CC} = GND	–50mA +20mA
I _{OUT}	DC Output Current	±50mA
I _{CC} /I _{GND}	DC V _{CC} /GND Current	±50mA
T _{STG}	Storage Temperature	-65°C to +150°C
TJ	Junction Temperature under Bias	150°C
T _L	Junction Lead Temperature (Soldering, 10 seconds)	260°C
P _D	Power Dissipation @ +85°C SOT23-5 SC70-5	200mW 150mW

Recommended Operating Conditions⁽¹⁾

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage Operation	1.65V to 5.5V
V _{CC}	Supply Voltage Data Retention	1.5V to 5.5V
V _{IN}	Input Voltage	0V to 5.5V
V _{OUT}	Output Voltage	0V to V _{CC}
T _A	Operating Temperature	-40°C to +85°C
t _r , t _f	Input Rise and Fall Time V _{CC} @ 1.8V, 2.5V ± 0.2V V _{CC} @ 3.3V ± 0.3V V _{CC} @ 5.0V ± 0.5V	Ons/V to 20ns/V Ons/V to 10ns/V Ons/V to 5ns/V
θ_{JA}	Thermal Resistance SOT23-5 SC70-5	300°C/W 425°C/W

Notes

1. Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

					TA	= +25	5°C	T _A = -40°C		
Symbol	Parameter	V _{CC} (V)	Cor	Conditions		Тур.	Max.	Min.	Max.	Unit
V _{IH}	HIGH Level	1.65–1.95			0.75 x V _{CC}			0.75 x V _{CC}		V
	Input Voltage	2.3–5.5			0.70 x V _{CC}			0.70 x V _{CC}		
V _{IL}	LOW Level Input	1.65–1.95					0.25 x V _{CC}		0.25 x V _{CC}	V
	Voltage	2.3–5.5					0.30 x V _{CC}		0.30 x V _{CC}	
V _{OH}	HIGH Level	1.65	$V_{IN} = V_{IL}$	$I_{OH} = -100 \mu A$	1.55	1.65		1.55		V
	Output Voltage	1.8			1.7	1.8		1.7		
		2.3			2.2	2.3		2.2		
		3.0			2.9	3.0		2.9		
		4.5			4.4	4.5		4.4		
		1.65		$I_{OH} = -4mA$	1.29	1.52		1.29		
		2.3		$I_{OH} = -8mA$	1.9	2.15		1.9		
		3.0		$I_{OH} = -16mA$	2.4	2.80		2.4		
		3.0		$I_{OH} = -24mA$	2.3	2.68		2.3		
		4.5		$I_{OH} = -32mA$	3.8	4.20		3.8		
V _{OL}	LOW Level	1.65	$V_{IN} = V_{IH}$	$I_{OL} = 100 \mu A$		0.0	0.1		0.08	V
	Output Voltage	1.8				0.0	0.1		0.1	
		2.3				0.0	0.1		0.1	
		3.0				0.0	0.1		0.1	
		4.5				0.0	0.1		0.1	
		1.65		I _{OL} = 4mA		0.08	0.24		0.24	
		2.3		I _{OL} = 8mA		0.10	0.3		0.3	
		3.0		I _{OL} = 16mA		0.15	0.4		0.4	
		3.0		$I_{OL} = 24mA$		0.22	0.55		0.55	
		4.5		$I_{OL} = 32mA$		0.22	0.55		0.55	
I _{IN}	Input Leakage Current	0–5.5	V _{IN} = 5.5\	, GND			±1		±10	μA
I _{OFF}	Power Off Leakage Current	0.0	V _{IN} or V _{OI}	_T = 5.5V			1		10	μA
I _{cc}	Quiescent Supply Current	1.65–5.5	V _{IN} = 5.5\	/, GND			2.0		20	μA

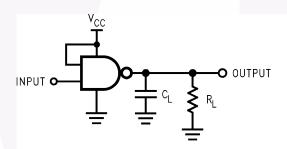
AC Electrical Characteristics

				T _A = +25°C		°C	T _A = -40°C to +85°C			Figure
Symbol	Parameter	V _{CC} (V)	Conditions	Min.	Тур.	Max.	Min.	Max.	Units	Number
t _{PLH} , t _{PHL}	Propagation Delay	1.65	C _L = 15pF,	2.0	5.4	11.4	2.0	12	ns	Figure 1
		1.8	$R_L = 1M\Omega$	2.0	4.5	9.5	2.0	10.0		Figure 3
		2.5 ± 0.2		0.8	3.0	6.5	0.8	7.0		
		3.3 ± 0.3		0.5	2.4	4.5	0.5	4.7		
		5.0 ± 0.5		0.5	2.0	3.9	0.5	4.1		
t _{PLH} , t _{PHL}	Propagation Delay	3.3 ± 0.3	C _L = 50pF,	1.5	2.9	5.0	1.5	5.2	ns	Figure 1
		5.0 ± 0.5	$R_L = 500\Omega$	0.8	2.4	4.3	0.8	4.5		Figure 3
C _{IN}	Input Capacitance	0			4				pF	
C _{PD}	Power Dissipation	3.3	(2)		24				pF	Figure 2
	Capacitance	5.0			30					

Note:

2. C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. (See Figure 2.) C_{PD} is related to I_{CCD} dynamic operating current by the expression: $I_{CCD} = (C_{PD})(V_{CC})(f_{IN}) + (I_{CC}\text{static})$.

AC Loading and Waveforms



 C_L includes load and stray capacitance Input PRR = 1.0MHz; t_w = 500ns

Figure 1. AC Test Circuit

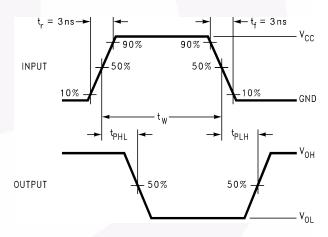
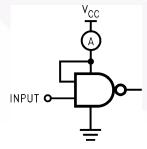


Figure 3. AC Waveforms



 $\begin{aligned} & \text{Input} = \text{AC Waveform; } t_r = t_f = 1.8 \text{ns;} \\ & \text{PRR} = 10 \text{MHz; Duty Cycle} = 50\% \end{aligned}$

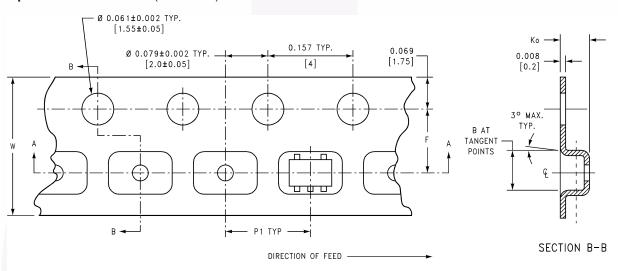
Figure 2. I_{CCD} Test Circuit

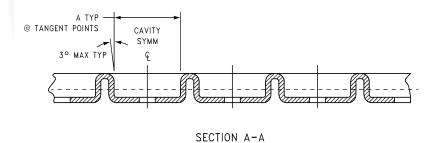
Tape and Reel Specifications

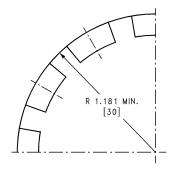
Tape Format for SC70 and SOT23

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
M5X, P5X	Leader (Start End)	125 (typ.)	Empty	Sealed
	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (typ.)	Empty	Sealed

Tape Dimensions inches (millimeters)







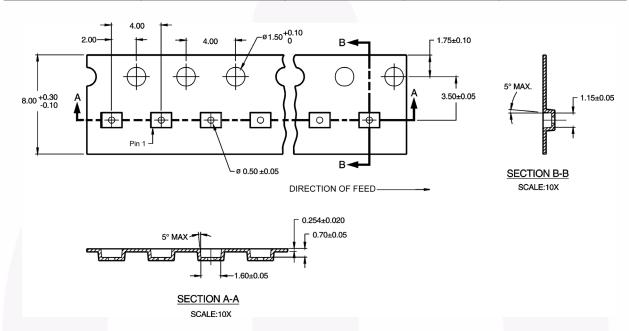
BEND RADIUS NOT TO SCALE

Package	Tape Size	Dim A	Dim B	Dim F	Dim K _o	Dim P1	Dim W
SC70-5	8mm	0.093 (2.35)	0.096 (2.45)	0.138 ± 0.004 (3.5 ± 0.10)	0.053 ± 0.004 (1.35 ± 0.10)	0.157 (4)	0.315 ± 0.004 (8 ± 0.1)
SOT23-5	8mm	0.130 (3.3)	0.130 (3.3)	0.138 ± 0.002 (3.5 ± 0.05)	0.055 ± 0.004 (1.4 ± 0.11)	0.157 (4)	0.315 ± 0.012 (8 ± 0.3)

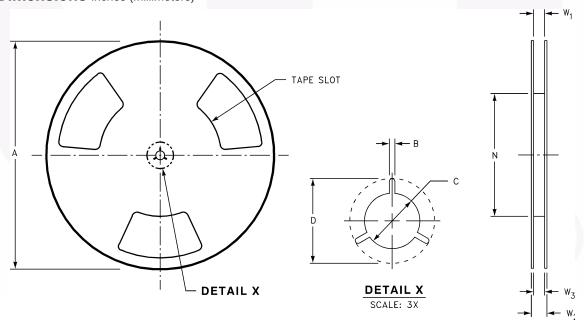
Tape and Reel Specifications (Continued)

Tape Format for MicroPak

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status	
L6X	Leader (Start End)	125 (typ.)	Empty	Sealed	
	Carrier	5000	Filled	Sealed	
	Trailer (Hub End)	75 (typ.)	Empty	Sealed	



Reel Dimensions inches (millimeters)



Tape Size	Α	В	С	D	N	W1	W2	W3
8mm	7.0	0.059	0.512	0.795	2.165	0.331 + 0.059/-0.000	0.567	W1 + 0.078/–0.039
	(177.8)	(1.50)	(13.00)	(20.20)	(55.00)	(8.40 + 1.50/–0.00)	(14.40)	(W1 + 2.00/–1.00)

Physical Dimensions

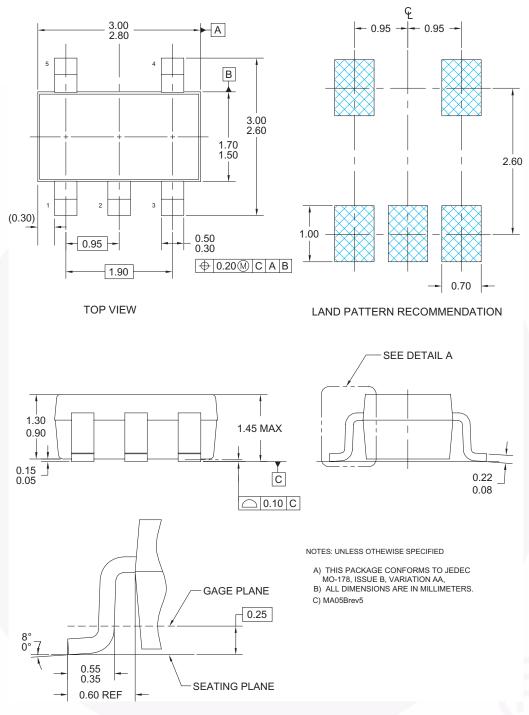


Figure 4. 5-Lead SOT23, JEDEC MO-178, 1.6mm

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Physical Dimensions (Continued) **SYMM** E 2.00±0.20-0.65 0.50 MIN 1.25±0.10 1.90 3 (0.25)-0.40 MIN 1.30 ⊕ 0.10(M) A B 0.65 LAND PATTERN RECOMMENDATION 1.30 SEE DETAIL A 1.00 0.80 0.10 0.10 2.10 ± 0.30 SEATING **PLANE GAGE** PLANE NOTES: UNLESS OTHERWISE SPECIFIED (R0.10) THIS PACKAGE CONFORMS TO EIAJ SC-88A, 1996. B) C) ALL DIMENSIONS ARE IN MILLIMETERS. DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. 0.20 DETAIL A

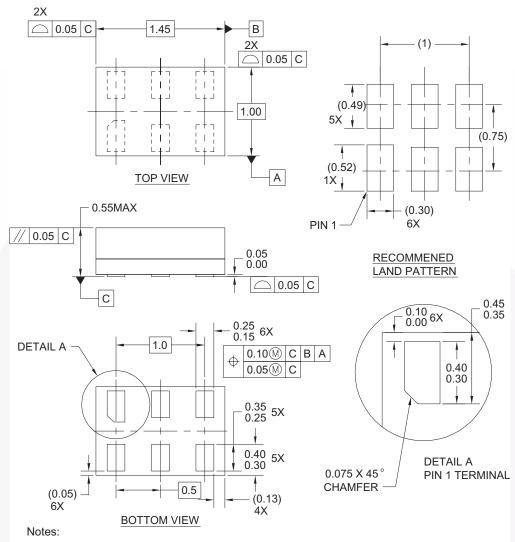
Figure 5. 5-Lead SC70, EIAJ SC-88a, 1.25mm Wide

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Physical Dimensions (Continued)



- 1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-1994

MAC06AREVC

Figure 6. 6-Lead MicroPak, 1.0mm Wide

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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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